	Operating			Sto	rage				
	temperature range		-55°C to + 105°C(Note 1) terr		nperature range		-10°C to + 60°C	(Note	(Note 3)
	Operating humidity range		40% to + 80%(Note :		orage midity range		40% to + 70%(Note 3)		)
	Applicable		DF3-22SC *	Арр	Applicable		UL1007 AWG24 to 28		
Poting	contact		DF3-2428SC *		ble		UL1061 AWG22 to 28		
Rating	Voltage					Voltage	30V AC/DC		
	Current		250V AC/DC AWG 22 to 24 : 3A/pin		CSA	Current	AIN/C 21 · 21		
			AWG 22 to 24 : 3A/p AWG 26 : 2A/pi AWG 28 : 1A/pi	in Rat			AWG 24 : 3A/pin AWG 26 : 2A/pin AWG 26 : 2A/pin AWG 28 : 1A/pin		◬
			Specif	fication	s				
	Item		Test method			Re	quirements	QT	AT
Constru	ction						•		
General exa		Visually a	and by measuring instrument.		Accor	ding to drawir	ng.	X	X
		Confirme	Confirmed visually.						X
-			a visually.					Х	^
	characteri				-			1	
Insulation resistance 50		500V DC	500V DC.			1000 <b>M</b> Ω <b>MIN</b> .			-
Voltage proof		650V AC	650V AC for 1 min.			No flashover or breakdown.			1_
Mechan	ical chara	cteristics			1			Х	
Mechanical			insertions and extractions.		1) No	damage. crag	ck or looseness of parts.		
	1				,			x	_
0.75 m		Frequence	cy 10 to 55 Hz, single amplitude		1) No	damage, crad	ck or looseness of parts.		+-
			, at 2 h, for 3 directions.			5.		Х	-
			90 m/s <sup>2</sup> duration of pulse 11 ms at 3 times for 3 lirections.			damage, crao	ck or looseness of parts.	x	_
Environr	mental cha	aracterist	ics						
	temperature Ti		Temperature -55 $\rightarrow$ 5 to 35 $\rightarrow$ 85 $\rightarrow$ 5 to 35 °c Time 30 $\rightarrow$ 5MAX $\rightarrow$ 30 $\rightarrow$ 5MAX min Under 5 cycles.				nce: 1000MΩ MIN.	X	
Rapid chan		-		X min	2) 110		ck or looseness of parts.	X	
Rapid chan temperature Damp heat	e	Under 5			1) Insu	ulation resistar	nce: 500MΩ MIN.		
Rapid chan temperature Damp heat (Steady sta Remarks Note 1:Inclu	e ate) Iding the tempe	Under 5 Exposed	cycles. at 40 ± 2 °c, 90 to 95 %, 96 h.		1) Insu	ulation resistar	·	X	
Rapid chan temperature Damp heat (Steady sta Remarks Note 1:Inclu Note 2:No c	e ite) iding the tempe ondensing.	Under 5 Exposed erature rise by	cycles. at 40 ± 2 °c, 90 to 95 %, 96 h.		1) Insu	ulation resistar	nce: 500MΩ MIN.		
Rapid chan temperature Damp heat (Steady sta Remarks Note 1:Inclu Note 2:No c Note 3:Apply	e Ite) Iding the tempe ondensing. y to an unused	Under 5 ( Exposed erature rise by	cycles. at 40 $\pm$ 2 °c, 90 to 95 %, 96 h. y current		1) Insu	ulation resistar	ce: 500MΩ MIN. ck or looseness of parts.	x	ate
Rapid chan iemperature Damp heat (Steady sta Remarks Note 1:Inclu Note 2:No c Note 3:Apply	e ite) iding the tempe ondensing. y to an unused	Under 5 d Exposed erature rise by a product on the product on the Descript DIS-	at 40 ± 2 °c, 90 to 95 %, 96 h.   y current   he packaged condition.   tion of revisions   H-00008205	Desi	1) Insi 2) No	ulation resistar damage, crac	ce: 500MΩ MIN. ck or looseness of parts. Checked SZ. 0N0	D 202	10312
Rapid chan temperature Damp heat (Steady sta Remarks Note 1:Inclu Note 2:No c Note 3:Apply	e ite) iding the tempe ondensing. y to an unused	Under 5 d Exposed erature rise by a product on the product on the Descript DIS-	cycles. at 40 ± 2 °c, 90 to 95 %, 96 h. y current he packaged condition.	Desi	1) Insu 2) No	Jlation resistar damage, crad	Checked SZ. 0N0 KJ. KATAYOSE	D 202 2005	10312 50105
Rapid chan iemperature Damp heat (Steady sta Remarks Note 1:Inclu Note 2:No c Note 3:Apply	e ite) iding the tempe ondensing. y to an unused	Under 5 d Exposed erature rise by a product on the product on the Descript DIS-	at 40 ± 2 °c, 90 to 95 %, 96 h.   y current   he packaged condition.   tion of revisions   H-00008205	Desi	1) Insu 2) No	Jlation resistar damage, crad Approved Checked	Checked SZ. 0N0 KJ. KATAY0SE KI. AKIYAMA	D 2005 2005	10312 50105 50105
Rapid chan iemperature Damp heat (Steady sta Remarks Note 1:Inclu Note 2:No c Note 3:Apply	e ite) iding the tempe ondensing. y to an unused	Under 5 d Exposed erature rise by a product on the product on the Descript DIS-	at 40 ± 2 °c, 90 to 95 %, 96 h.   y current   he packaged condition.   tion of revisions   H-00008205	Desi	1) Insu 2) No	Approved Checked Designed	Checked SZ. 0N0 KJ. KATAYOSE KI. AKIYAMA TH. ARAI	D 2005 2005 2005	10312 50105 50105 50105
Rapid chan emperature (Steady sta Remarks Note 1:Inclu Note 2:No c Note 3:Apply Local A 1 Jnless oth	e Ite) Iding the temper ondensing. y to an unused nt nerwise spece	Under 5 ( Exposed erature rise by product on the product on the Descript DIS- cified , refer	at 40 ± 2 °c, 90 to 95 %, 96 h.   y current   he packaged condition.   ion of revisions   H-00008205   r to IEC 60512.	Desi	1) Insu 2) No	Jlation resistar damage, crad Approved Checked	Checked SZ. 0N0 KJ. KATAYOSE KI. AKIYAMA TH. ARAI TH. ARAI	D 202 2009 2009 2009 2009	10312 50105 50105 50105 50105
Rapid chan iemperature (Steady sta Remarks Note 1:Inclu Note 2:No c Note 3:Apply Local Loc	e Ite) Iding the temper ondensing. y to an unused nt nerwise spece	Under 5 ( Exposed erature rise by product on the product on the Descript DIS- cified , refer	at 40 ± 2 °c, 90 to 95 %, 96 h.   y current   he packaged condition.   tion of revisions   H-00008205	Desi	1) Insu 2) No	Jlation resistar damage, crad Approved Checked Designed Drawn	Checked SZ. 0N0 KJ. KATAYOSE KI. AKIYAMA TH. ARAI	D 202 2009 2009 2009 2009	10312 50105 50105 50105 50105
Rapid chan temperature (Steady sta Remarks Note 1:Inclu Note 2:No c Note 3:Apply Local Loc	e tte) tding the temper ondensing. y to an unused nt nerwise spece Qualification 1	Under 5 ( Exposed erature rise by product on the product on the Description DIS- cified , reference Fest AT:Ass	at 40 ± 2 °c, 90 to 95 %, 96 h.   y current   he packaged condition.   ion of revisions   H-00008205   r to IEC 60512.	Desi SN.	1) Insu 2) No gned MIWA	Jlation resistar damage, crad Approved Checked Designed Drawn	Checked SZ. 0N0 KJ. KATAYOSE KI. AKIYAMA TH. ARAI TH. ARAI	D 202 2009 2009 2009 2009	10312 50105 50105 50105 50105

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